

HDAM-11-12.0-S-13-2



HDAF-11-08.0-S-13-2

(2,00 mm) .0787"

HDAM, HDAF SERIES

RUGGED ELEVATED HIGH DENSITY ARRAY

HDAM Mates with:
HDAF
HDAF Mates with:
HDAM

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDAM or www.samtec.com?HDAF

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Plating:

Au or Sn over

50µ" (1,27 µm) Ni

Current Rating:

3.4 A per pin

(6 adjacent pins powered)

Operating Temp Range:

-55°C to +125°C

Contact Resistance: 19 mΩ

Working Voltage: 200 VAC

Mated Cycles: 100

RoHS Compliant: Yes

Lead-Free Solderable: Yes

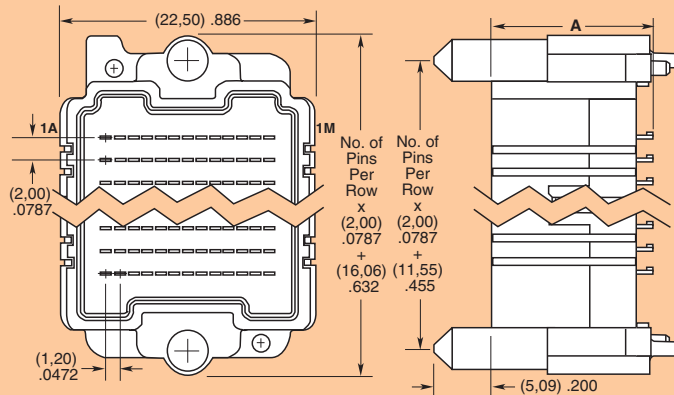
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

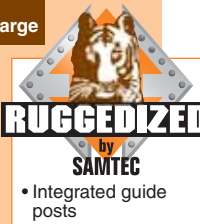


FILE NO. E111594

HDAM	NO. OF PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OTHER OPTION
	-11, -15, -23	Specify LEAD STYLE from chart	-S = 30µ" (0,76 µm) Gold on contact area, Matte Tin on tails and guide pins	-13	-2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/0.7% Cu Solder Charge	-P = Pick & Place Pad



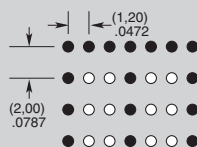
LEAD STYLE	A
-12.0	(14,41) .567
-17.0	(19,41) .764



HDAM/HDAF 35 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	9 GHz / 18 Gbps
Differential Pair Signaling	9 GHz / 18 Gbps

*Data based on simulations using Final Inch® design.
*Performance data includes effects of a non-optimized PCB.
Performance data for other stack heights and complete test data available at www.samtec.com?HDAM, www.samtec.com?HDAF or contact sig@samtec.com

DIFFERENTIAL APPLICATIONS



ARRAY	PAIR COUNT*
11x13	44
15x13	60
23x13	92

*2:1 S:G Ratio

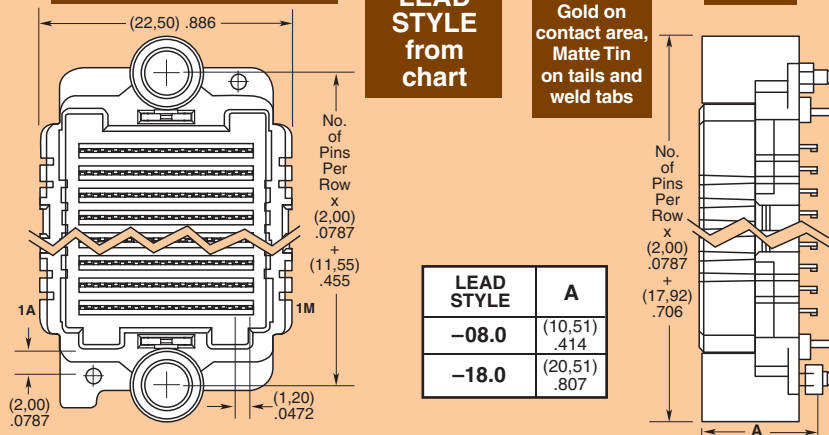
ALSO AVAILABLE (MOQ Required)

- Tin-Lead Solder Charge
 - Other platings
- Contact Samtec.

Note: HD Mezz is a trademark of Molex Incorporated

Note: Some lengths, styles and options are non-standard, non-returnable.

HDAF	NO. OF PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OTHER OPTION
	-11, -15, -23	Specify LEAD STYLE from chart	-S = 30µ" (0,76 µm) Gold on contact area, Matte Tin on tails and weld tabs	-13	-2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/ 0.7% Cu Solder Charge	-P = Pick & Place Pad



LEAD STYLE	A
-08.0	(10,51) .414
-18.0	(20,51) .807



Due to technical progress, all its designs, specifications and components are subject to change without notice.

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